



WLCSP15_6-3-6

wafer level chip-size package; 15 bumps (6-3-6); 0.4 mm pitch; 2.37 x 1.17 x 0.57 mm body

7 June 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP15
Package style descriptive code	UC (uncased chip)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	11-2-2010
Manufacturer package code	WLCSP15

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.32	-	2.37	2.42	mm
E	package width	1.12	-	1.17	1.22	mm
A	seated height	0.54	-	0.57	0.6	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	15	-	

2. Package outline

WLCSP15: wafer level chip-size package; 15 bumps (6-3-6)

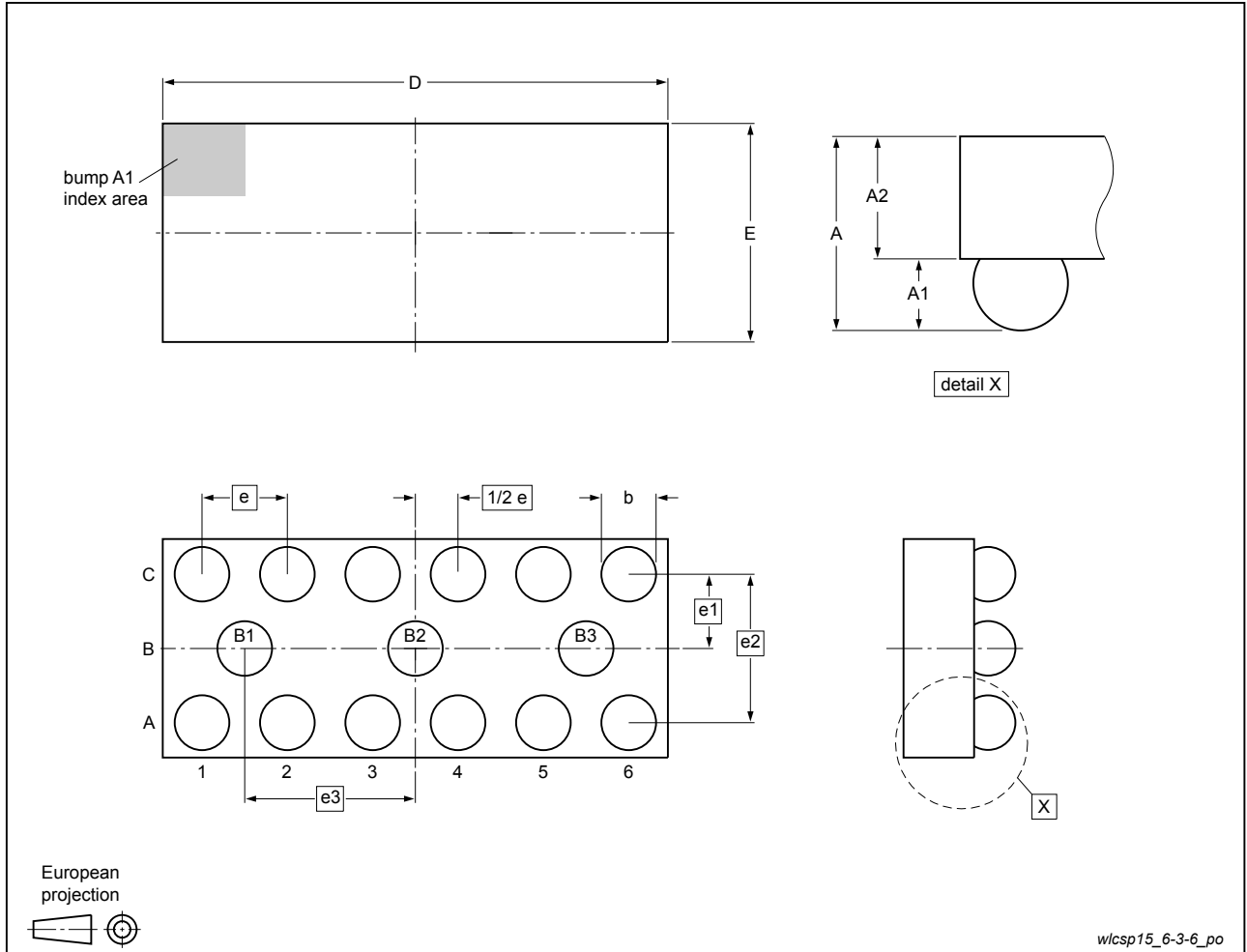


Fig. 1. Package outline WLCSP15 (WLCSP15_6-3-6)

3. Legal information

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